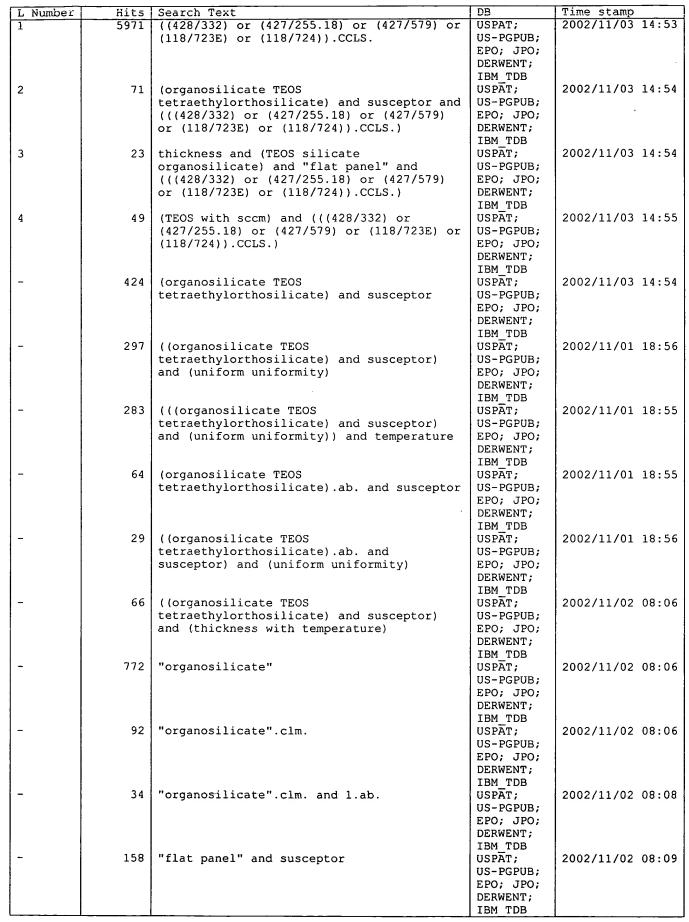
#3







4	
	•

-	11	("flat panel" and susceptor) and	USPAT;	2002/11/02 09:05
ļ		("organosilicate" TEOS)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	!		IBM TDB	
l _	426	TEOS with sccm	USPAT;	2002/11/03 14:54
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
1_	59	(TEOS with sccm) with "800"	USPAT;	2002/11/02 09:07
-	33	(1EOS WIEN SCOM) WICH GOO	US-PGPUB;	2002/11/02 03.07
			EPO; JPO;	
			DERWENT;	
			IBM TDB	ł
	15	((TEOS with sccm) with "800") with (He	USPAT;	2002/11/02 09:07
~	13	helium) with (oxygen "O.sub.2")		2002/11/02 09.07
		nerium) with (oxygen "O.Sub.2")	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
ł			IBM_TDB	
-	90	(TEOS with sccm) with "300"	USPAT;	2002/11/02 09:07
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	13	((TEOS with sccm) with "300") with (He	USPAT;	2002/11/02 09:33
		helium) with (oxygen "O.sub.2")	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	10	"power density" with SCCM with TEOS	USPAT;	2002/11/02 10:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
] -	445	"300 mm wafers"	USPAT;	2002/11/03 10:10
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	644	thickness and (TEOS silicate	USPAT;	2002/11/03 14:54
1	""	organosilicate) and "flat panel"	US-PGPUB; .	
1	1	l little punet	EPO; JPO;	
	[DERWENT;	
			IBM TDB	
l _	183	(thickness with (wariation dowistion	_	2002/11/02 14-52
-	183	·	USPAT;	2002/11/03 14:52
		uniformity uniform)) and (TEOS silicate	US-PGPUB;	
		organosilicate) and "flat panel"	EPO; JPO;	
	1		DERWENT;	}
L	L		IBM_TDB	